# Quad Analog Switch/ Quad Multiplexer

The MC14016B quad bilateral switch is constructed with MOS P-channel and N-channel enhancement mode devices in a single monolithic structure. Each MC14016B consists of four independent switches capable of controlling either digital or analog signals. The quad bilateral switch is used in signal gating, chopper, modulator, demodulator and CMOS logic implementation.

#### **Features**

- Diode Protection on All Inputs
- Supply Voltage Range = 3.0 Vdc to 18 Vdc
- Linearized Transfer Characteristics
- Low Noise 12 nV/ $\sqrt{\text{Cycle}}$ , f  $\geq$  1.0 kHz typical
- Pin-for-Pin Replacements for CD4016B, CD4066B (Note improved transfer characteristic design causes more parasitic coupling capacitance than CD4016)
- For Lower R<sub>ON</sub>, Use The HC4016 High–Speed CMOS Device or The MC14066B
- This Device Has Inputs and Outputs Which Do Not Have ESD Protection. Antistatic Precautions Must Be Taken
- These Devices are Pb-Free and are RoHS Compliant

#### MAXIMUM RATINGS (Voltages Referenced to VSS)

Symbol	Parameter	Value	Unit
$V_{DD}$	DC Supply Voltage Range	-0.5 to +18.0	V
V <sub>in</sub> , V <sub>out</sub>	Input or Output Voltage Range (DC or Transient)	-0.5 to V <sub>DD</sub> + 0.5	V
l <sub>in</sub>	Input Current (DC or Transient) per Control Pin	±10	mA
I <sub>SW</sub>	Switch Through Current	±25	mA
P <sub>D</sub>	Power Dissipation, per Package (Note 1)	500	mW
T <sub>A</sub>	Ambient Temperature Range	-55 to +125	°C
T <sub>stg</sub>	Storage Temperature Range	-65 to +150	°C
TL	Lead Temperature (8–Second Soldering)	260	°C

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

1. Temperature Derating:

Plastic "P and D/DW" Packages: - 7.0 mW/°C From 65°C To 125°C

This device contains protection circuitry to guard against damage due to high static voltages or electric fields. However, precautions must be taken to avoid applications of any voltage higher than maximum rated voltages to this high–impedance circuit. For proper operation,  $V_{in}$  and  $V_{out}$  should be constrained to the range  $V_{SS} \leq (V_{in} \text{ or } V_{out}) \leq V_{DD}.$ 

Unused inputs must always be tied to an appropriate logic voltage level (e.g., either  $V_{SS}$  or  $V_{DD}$ ). Unused outputs must be left open.



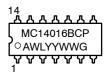
## ON Semiconductor®

http://onsemi.com

MARKING DIAGRAMS



PDIP-14 P SUFFIX CASE 646



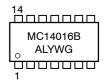


SOIC-14 D SUFFIX CASE 751A





SOEIAJ-14 F SUFFIX CASE 965



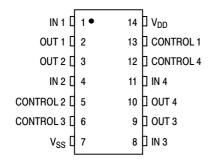
A = Assembly Location

 $\begin{array}{ll} WL,\,L &= Wafer\,Lot \\ YY,\,Y &= Year \\ WW,\,W &= Work\,Week \\ G &= Pb-Free\,Indicator \end{array}$ 

## **ORDERING INFORMATION**

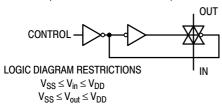
See detailed ordering and shipping information in the package dimensions section on page 2 of this data sheet.

## **PIN ASSIGNMENT**

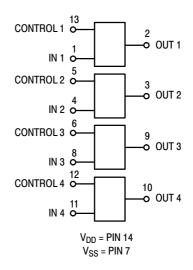


## **LOGIC DIAGRAM**

(1/4 OF DEVICE SHOWN)



## **BLOCK DIAGRAM**



Control	Switch
0 = V <sub>SS</sub>	Off
1 = V <sub>DD</sub>	On

## **ORDERING INFORMATION**

Device	Package	Shipping <sup>†</sup>
MC14016BCPG	PDIP-14 (Pb-Free)	500 / Tube
MC14016BDG	SOIC-14 (Pb-Free)	55 Units / Rail
MC14016BDR2G	SOIC-14 (Pb-Free)	2500 / Tape & Reel
MC14016BFELG	SOEIAJ-14 (Pb-Free)	2000 / Tape & Reel

<sup>†</sup>For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

## **ELECTRICAL CHARACTERISTICS** (Voltages Referenced to V<sub>SS</sub>)

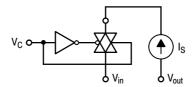
			V <sub>DD</sub>		C 25°C			125°C			
Characteristic	Figure	Symbol	Vdc	Min	Max	Min	Typ <sup>(2)</sup>	Max	Min	Max	Unit
Input Voltage Control Input	1	V <sub>IL</sub>	5.0 10 15	- - -	- -	- -	1.5 1.5 1.5	0.9 0.9 0.9	- -	_ _	Vdc
		V <sub>IH</sub>	5.0 10 15	- - -	- - -	3.0 8.0 13	2.0 6.0 11	- - -	- - -	- - -	Vdc
Input Current Control	-	I <sub>in</sub>	15	_	±0.1	_	±0.00001	±0.1	_	± 1.0	μAdc
Input Capacitance Control Switch Input Switch Output Feed Through	-	C <sub>in</sub>	- - - -	- - - -	- - -	- - - -	5.0 5.0 5.0 0.2	- - - -	- - - -	- - -	pF
Quiescent Current (Per Package) (3)	2,3	I <sub>DD</sub>	5.0 10 15	- - -	0.25 0.5 1.0	- - -	0.0005 0.0010 0.0015	0.25 0.5 1.0	- - -	7.5 15 30	μAdc
"ON" Resistance $(V_C = V_{DD}, R_L = 10 \text{ k}\Omega)$	4,5,6	R <sub>ON</sub>									Ω
$(V_{in} = + 10 \text{ Vdc})$ $(V_{in} = + 0.25 \text{ Vdc}) V_{SS} = 0 \text{ Vdc}$ $(V_{in} = + 5.6 \text{ Vdc})$			10	- - -	600 600 600	- - -	260 310 310	660 660 660	- - -	840 840 840	
$(V_{in} = + 15 \text{ Vdc})$ $(V_{in} = + 0.25 \text{ Vdc}) V_{SS} = 0 \text{ Vdc}$ $(V_{in} = + 9.3 \text{ Vdc})$			15	- - -	360 360 360	- - -	260 260 300	400 400 400	- - -	520 520 520	
$\Delta$ "ON" Resistance Between any 2 circuits in a common package $ \begin{array}{l} (V_C = V_{DD}) \\ (V_{in} = +5.0 \ \text{Vdc}, \ V_{SS} = -5.0 \ \text{Vdc}) \\ (V_{in} = +7.5 \ \text{Vdc}, \ V_{SS} = -7.5 \ \text{Vdc}) \end{array} $	-	ΔR <sub>ON</sub>	5.0 7.5		_ _		15 10	- -		_ _	Ω
Input/Output Leakage Current $ \begin{aligned} &(V_C = V_{SS}) \\ &(V_{in} = + 7.5,  V_{out} = - 7.5  \text{Vdc}) \\ &(V_{in} = - 7.5,  V_{out} = + 7.5  \text{Vdc}) \end{aligned} $	-	-	7.5 7.5	_ _	±0.1 ±0.1	- -	±0.0015 ±0.0015	±0.1 ±0.1	- -	± 1.0 ± 1.0	μAdc

<sup>NOTE: All unused inputs must be returned to V<sub>DD</sub> or V<sub>SS</sub> as appropriate for the circuit application.
2. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.
3. For voltage drops across the switch (ΔV<sub>switch</sub>) > 600 mV ( > 300 mV at high temperature), excessive V<sub>DD</sub> current may be drawn; i.e., the current out of the switch may contain both V<sub>DD</sub> and switch input components. The reliability of the device will be unaffected unless the Maximum Ratings are exceeded. (See first page of this data sheet.) Reference Figure 14.</sup> 

## **ELECTRICAL CHARACTERISTICS** (4) $(C_L = 50 \text{ pF}, T_A = 25^{\circ}\text{C})$

			V		1	1	1
Characteristic	Figure	Symbol	V <sub>DD</sub> Vdc	Min	Typ <sup>(5)</sup>	Max	Unit
Propagation Delay Time (V <sub>SS</sub> = 0 Vdc) $V_{in} \text{ to } V_{out} $ (V <sub>C</sub> = V <sub>DD</sub> , R <sub>L</sub> = 10 k $\Omega$ )	7	t <sub>PLH</sub> , t <sub>PHL</sub>	5.0 10 15	- - -	15 7.0 6.0	45 20 15	ns
Control to Output $ (V_{in} \leq 10 \text{ Vdc}, R_L = 10 \text{ k}\Omega) $	8	t <sub>PHZ</sub> , t <sub>PLZ</sub> , t <sub>PZH</sub> , t <sub>PZL</sub>	5.0 10 15	- - -	34 20 15	120 110 100	ns
Crosstalk, Control to Output ( $V_{SS}$ = 0 Vdc) ( $V_{C}$ = $V_{DD}$ , $R_{in}$ = 10 k $\Omega$ , $R_{out}$ = 10 k $\Omega$ , f = 1.0 kHz)	9	-	5.0 10 15		30 50 100	- - -	mV
Crosstalk between any two switches ( $V_{SS} = 0 \text{ Vdc}$ ) ( $R_L = 1.0 \text{ k}\Omega$ , $f = 1.0 \text{ MHz}$ , crosstalk = $20 \log_{10} \frac{V_{out1}}{V_{out2}}$ )	-	1	5.0	ı	- 80	1	dB
Noise Voltage (V <sub>SS</sub> = 0 Vdc) (V <sub>C</sub> = V <sub>DD</sub> , f = 100 Hz)	10,11	-	5.0 10 15	- - -	24 25 30	- - -	nV/√Cycle
(V <sub>C</sub> = V <sub>DD</sub> , f = 100 kHz)			5.0 10 15	- - -	12 12 15	- - -	
Second Harmonic Distortion ( $V_{SS} = -5.0 \text{ Vdc}$ ) ( $V_{in} = 1.77 \text{ Vdc}$ , RMS Centered @ 0.0 Vdc, R <sub>L</sub> = 10 k $\Omega$ , f = 1.0 kHz)	_	_	5.0	I	0.16	_	%
$\label{eq:loss_substitute} \begin{split} & \text{Insertion Loss }(V_C = V_{DD},  V_{in} = 1.77  \text{Vdc}, \\ & V_{SS} = -5.0  \text{Vdc},  \text{RMS centered} = 0.0  \text{Vdc},  \text{f} = 1.0  \text{MHz}) \\ & I_{IOSS} = 20  \text{log}_{10}  \frac{V_{out}}{V_{in}}) \\ & (R_L = 1.0  \text{k}\Omega) \\ & (R_L = 10  \text{k}\Omega) \\ & (R_L = 100  \text{k}\Omega) \\ & (R_L = 1.0  \text{M}\Omega) \\ \end{aligned}$	12		5.0	1 1 1 1	2.3 0.2 0.1 0.05	- - -	dB
$Bandwidth (-3.0 \text{ dB}) \\ (V_C = V_{DD}, V_{in} = 1.77 \text{ Vdc}, V_{SS} = -5.0 \text{ Vdc}, \\ RMS \text{ centered } @ 0.0 \text{ Vdc}) \\ (R_L = 1.0 \text{ k}\Omega) \\ (R_L = 10 \text{ k}\Omega) \\ (R_L = 100 \text{ k}\Omega) \\ (R_L = 1.0 \text{ M}\Omega) \\ (R_L = 1.0 \text{ M}\Omega)$	12,13	BW	5.0	1 1 1	54 40 38 37	- - -	MHz
$\label{eq:continuous_continuous} \begin{split} & \text{OFF Channel Feedthrough Attenuation} \\ & (V_{SS} = -5.0 \text{ Vdc}) \\ & (V_{C} = V_{SS}, 20 \log_{10}  \frac{V_{out}}{V_{in}} = -50  \text{dB}) \\ & (R_{L} = 1.0  \text{k}\Omega) \\ & (R_{L} = 10  \text{k}\Omega) \\ & (R_{L} = 100  \text{k}\Omega) \\ & (R_{L} = 1.0  \text{M}\Omega) \end{split}$	-	-	5.0	- - -	1250 140 18 2.0	- - - -	kHz

<sup>4.</sup> The formulas given are for typical characteristics only at 25°C.
5. Data labelled "Typ" is not to be used for design purposes but is intended as an indication of the IC's potential performance.



$$\begin{split} V_{IL} \colon V_{C} \text{ is raised from } V_{SS} \text{ until } V_{C} &= V_{IL}. \\ \text{at } V_{C} &= V_{IL} \colon I_{S} = \pm 10 \ \mu\text{A with } V_{in} = V_{SS}, \ V_{out} = V_{DD} \text{ or } V_{in} = V_{DD}, \ V_{out} = V_{SS}. \end{split}$$

 $V_{IH}$ : When  $V_C$  =  $V_{IH}$  to  $V_{DD}$ , the switch is ON and the  $R_{ON}$  specifications are met.

Figure 1. Input Voltage Test Circuit

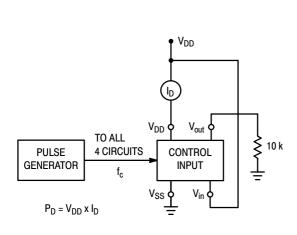


Figure 2. Quiescent Power Dissipation Test Circuit

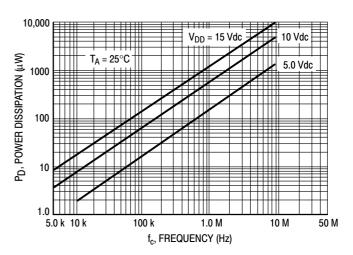
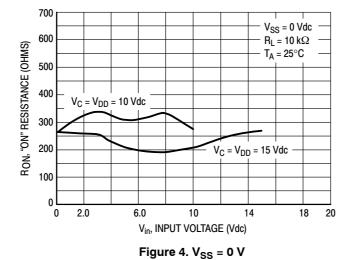


Figure 3. Typical Power Dissipation per Circuit (1/4 of device shown)

## TYPICAL RON versus INPUT VOLTAGE



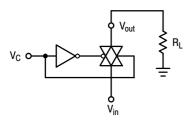


Figure 5. R<sub>ON</sub> Characteristics Test Circuit

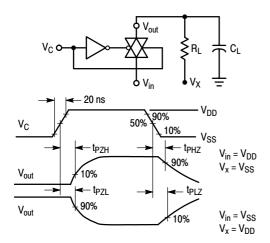


Figure 7. Turn-On Delay Time Test Circuit and Waveforms

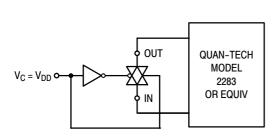


Figure 9. Noise Voltage Test Circuit

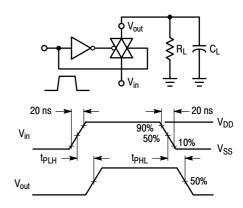


Figure 6. Propagation Delay Test Circuit and Waveforms

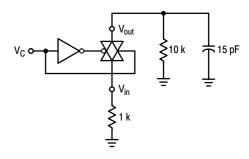


Figure 8. Crosstalk Test Circuit

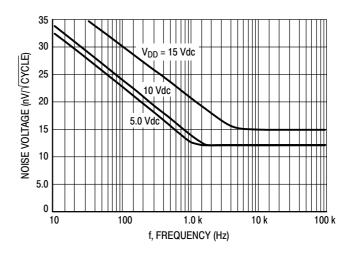


Figure 10. Typical Noise Characteristics

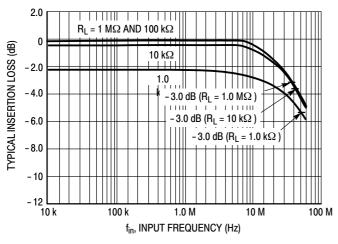


Figure 11. Typical Insertion Loss/Bandwidth Characteristics

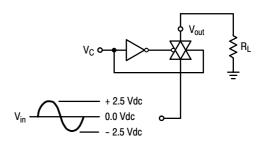


Figure 12. Frequency Response Test Circuit

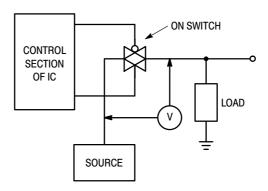


Figure 13.  $\Delta V$  Across Switch

#### **APPLICATIONS INFORMATION**

Figure A illustrates use of the Analog Switch. The 0-to-5 V Digital Control signal is used to directly control a 5  $V_{p-p}$  analog signal.

The digital control logic levels are determined by  $V_{DD}$  and  $V_{SS}$ . The  $V_{DD}$  voltage is the logic high voltage; the  $V_{SS}$  voltage is logic low. For the example,  $V_{DD}$  = +5 V logic high at the control inputs;  $V_{SS}$  = GND = 0 V logic low.

The maximum analog signal level is determined by  $V_{DD}$  and  $V_{SS}$ . The analog voltage must not swing higher than  $V_{DD}$  or lower than  $V_{SS}$ .

The example shows a 5  $V_{p-p}$  signal which allows no margin at either peak. If voltage transients above  $V_{DD}$  and/or below  $V_{SS}$  are anticipated on the analog channels, external diodes  $(D_x)$  are recommended as shown in Figure B. These diodes should be small signal types able to absorb the maximum anticipated current surges during clipping.

The *absolute* maximum potential difference between  $V_{DD}$  and  $V_{SS}$  is 18.0 V. Most parameters are specified up to 15 V which is the *recommended* maximum difference between  $V_{DD}$  and  $V_{SS}$ .

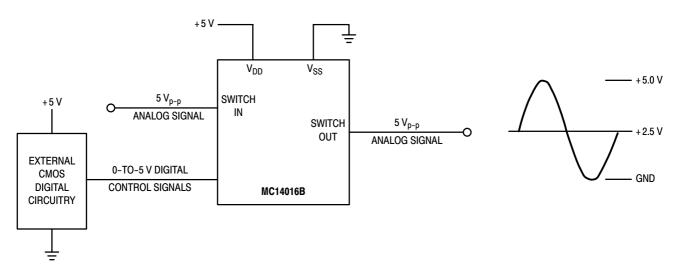


Figure A. Application Example

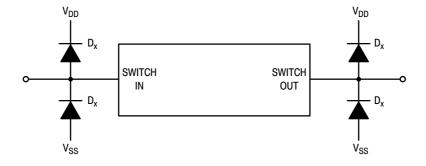
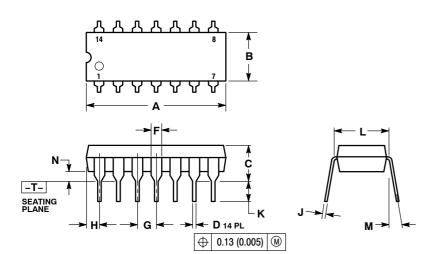


Figure B. External Germanium or Schottky Clipping Diodes

## **PACKAGE DIMENSIONS**

PDIP-14 CASE 646-06 ISSUE P

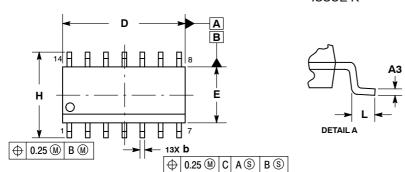


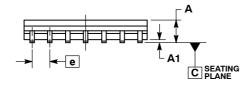
- NOTES:
  1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
  2. CONTROLLING DIMENSION: INCH.
  3. DIMENSION L TO CENTER OF LEADS WHEN FORMED PARALLEL.
  4. DIMENSION B DOES NOT INCLUDE MOLD FLASH.
  5. ROUNDED CORNERS OPTIONAL.

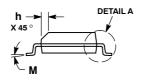
	INC	HES	MILLIM	IETERS	
DIM	MIN	MAX	MIN	MAX	
Α	0.715	0.770	18.16	19.56	
В	0.240	0.260	6.10	6.60	
С	0.145	0.185	3.69	4.69	
D	0.015	0.021	0.38	0.53	
F	0.040	0.070	1.02	1.78	
G	0.100	BSC	2.54 BSC		
Н	0.052	0.095	1.32	2.41	
J	0.008	0.015	0.20	0.38	
K	0.115	0.135	2.92	3.43	
L	0.290	0.310	7.37	7.87	
M		10 °		10 °	
N	0.015	0.039	0.38	1.01	

## **PACKAGE DIMENSIONS**

## SOIC-14 NB CASE 751A-03 ISSUE K







- NOTES:

  1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.

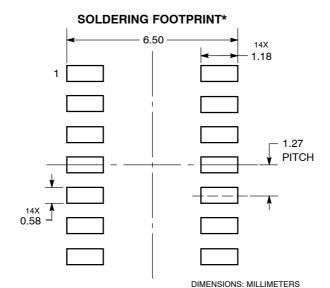
  2. CONTROLLING DIMENSION: MILLIMETERS.

  3. DIMENSION & DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF AT MAXIMUM MATERIAL CONDITION.

  4. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSIONS.

  5. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.

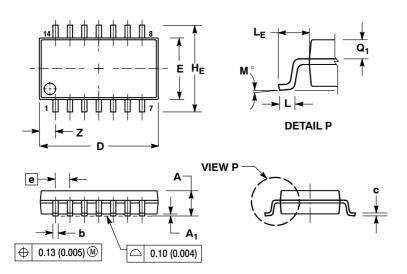
	MILLIN	IETERS	INCHES		
DIM	MIN	MAX	MIN	MAX	
Α	1.35	1.75	0.054	0.068	
A1	0.10	0.25	0.004	0.010	
А3	0.19	0.25	0.008	0.010	
b	0.35	0.49	0.014	0.019	
D	8.55	8.75	0.337	0.344	
Е	3.80	4.00	0.150	0.157	
е	1.27	1.27 BSC		BSC	
Н	5.80	6.20	0.228	0.244	
h	0.25	0.50	0.010	0.019	
L	0.40	1.25	0.016	0.049	
М	0 °	7°	0 °	7°	



\*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

#### PACKAGE DIMENSIONS

SOEIAJ-14 CASE 965-01 ISSUE B



#### NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- 2. CONTROLLING DIMENSION: MILLIMFTER
- DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15 (0.006) PER SIDE.
- TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY.
- 5. THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

	MILLIN	IETERS	INC	HES
DIM	MIN	MAX	MIN	MAX
Α		2.05		0.081
A <sub>1</sub>	0.05	0.20	0.002	0.008
b	0.35	0.50	0.014	0.020
С	0.10	0.20	0.004	0.008
D	9.90	10.50	0.390	0.413
Е	5.10	5.45	0.201	0.215
е	1.27	1.27 BSC		BSC
HE	7.40	8.20	0.291	0.323
L	0.50	0.85	0.020	0.033
LE	1.10	1.50	0.043	0.059
M	0 °	10°	0 °	10°
$Q_1$	0.70	0.90	0.028	0.035
Z		1.42		0.056

ON Semiconductor and are registered trademarks of Semiconductor Components Industries, LLC (SCILLC). SCILLC reserves the right to make changes without further notice to any products herein. SCILLC makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does SCILLC assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. "Typical" parameters which may be provided in SCILLC data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. SCILLC does not convey any license under its patent rights nor the rights of others. SCILLC products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the SCILLC product could create a situation where personal injury or death may occur. Should Buyer purchase or use SCILLC products for any such unintended or unauthorized application, Buyer shall indemnify and hold SCILLC and its officers, employees, subsidiaries, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that SCILLC was negligent regarding the design or manufacture of the part. SCILLC is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

#### **PUBLICATION ORDERING INFORMATION**

#### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor P.O. Box 5163, Denver, Colorado 80217 USA Phone: 303–675–2175 or 800–344–3860 Toll Free USA/Canada

Fax: 303-675-2176 or 800-344-3867 Toll Free USA/Canada Email: orderlit@onsemi.com N. American Technical Support: 800-282-9855 Toll Free USA/Canada

Europe, Middle East and Africa Technical Support: Phone: 421 33 790 2910

Japan Customer Focus Center Phone: 81–3–5773–3850 ON Semiconductor Website: www.onsemi.com

Order Literature: http://www.onsemi.com/orderlit

For additional information, please contact your local Sales Representative



Мы молодая и активно развивающаяся компания в области поставок электронных компонентов. Мы поставляем электронные компоненты отечественного и импортного производства напрямую от производителей и с крупнейших складов мира.

Благодаря сотрудничеству с мировыми поставщиками мы осуществляем комплексные и плановые поставки широчайшего спектра электронных компонентов.

Собственная эффективная логистика и склад в обеспечивает надежную поставку продукции в точно указанные сроки по всей России.

Мы осуществляем техническую поддержку нашим клиентам и предпродажную проверку качества продукции. На все поставляемые продукты мы предоставляем гарантию.

Осуществляем поставки продукции под контролем ВП МО РФ на предприятия военно-промышленного комплекса России, а также работаем в рамках 275 ФЗ с открытием отдельных счетов в уполномоченном банке. Система менеджмента качества компании соответствует требованиям ГОСТ ISO 9001.

Минимальные сроки поставки, гибкие цены, неограниченный ассортимент и индивидуальный подход к клиентам являются основой для выстраивания долгосрочного и эффективного сотрудничества с предприятиями радиоэлектронной промышленности, предприятиями ВПК и научноисследовательскими институтами России.

С нами вы становитесь еще успешнее!

#### Наши контакты:

Телефон: +7 812 627 14 35

Электронная почта: sales@st-electron.ru

Адрес: 198099, Санкт-Петербург,

Промышленная ул, дом № 19, литера Н,

помещение 100-Н Офис 331